August 19, 2008

Rambus to Showcase High-Speed Memory Technologies and Architectures at IDF 2008

Aug 19, 2008 (BUSINESS WIRE) -- Rambus Inc. (Nasdaq:RMBS):

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Who:      Rambus Inc. (Nasdaq: RMBS)

Where:    Intel Developer Forum
          Moscone Center West
          800 Howard Street
          San Francisco, CA
          Booth #712

When:     August 19-21, 2008
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Join Rambus at Intel Developer Forum 2008 for demos and displays of Rambus' latest technology developments:

-- The Terabyte Bandwidth Initiative, featuring new memory signaling innovations that facilitate data rates of 16Gbps, enables a future memory architecture that can deliver an unprecedented Terabyte per second (TB/s) of memory bandwidth (1 terabyte = 1,024 gigabytes) to a single System-on-Chip (SoC). Innovations include the industry's first differential signaling for both data and command/address (C/A); FlexLink(TM) C/A, the industry's first full-speed, point-to-point C/A link; and 32X Data Rate technology (32 data bits per input clock cycle).

-- Low power signaling technology operating at 6.25Gbps with a power-performance metric of 2.2mW/Gbps.

-- PLAYSTATION(R)3 (PS3(TM)) open demo board, featuring the XDR(TM) memory architecture. The Rambus XDR memory interface and FlexIO(TM) processor bus on the Cell Broadband Engine(TM) enable an unprecedented aggregate bandwidth of over 65GB/s in the PS3.

-- TI DLP(R) projector open demo board, featuring the XDR memory architecture. This architecture, including XDR DRAM , XDR memory controller (XMC), XDR IO cell (XIO), and XDR clock generator (XCG), delivers memory bandwidth up to 8.0GB/s in the latest generation of HD front projectors.

About Rambus Inc.

Rambus is one of the world's premier technology licensing companies specializing in the invention and design of high-speed memory architectures. Since its founding in 1990, the Company's patented innovations, breakthrough technologies and renowned integration expertise have helped industry-leading chip and system companies bring superior products to market. Rambus' technology and products solve customers' most complex chip and system-level interface challenges enabling unprecedented performance in computing, communications and consumer electronics applications. Rambus licenses both its world-class patent portfolio as well as its family of leadership and industry-standard interface products. Headquartered in Los Altos, California, Rambus has regional offices in North Carolina, India, Germany, Japan, and Taiwan. Additional information is available at www.rambus.com.

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